3.5x2.8 mm SMD CHIP LED LAMP

Part Number: AA3529ZG24ZS GREEN

PRELIMINARY SPEC



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- WHITE SMD PACKAGE, SILICONE RESIN.
- LOW THERMAL RESISTANCE.
- PACKAGE: 1500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 2a.
- RoHS COMPLIANT.

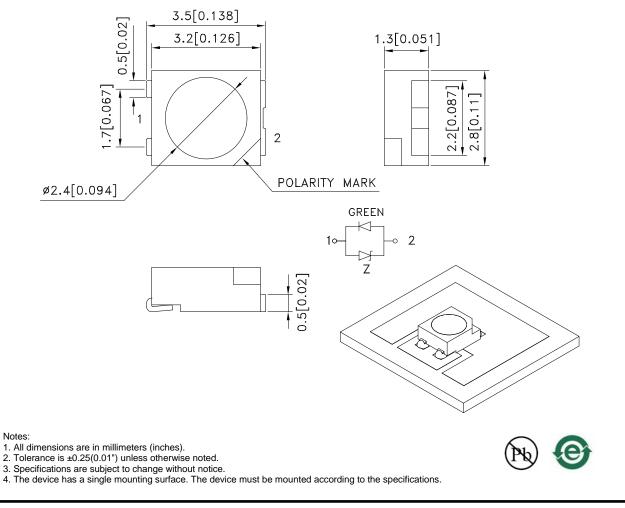
Description

The Green source color devices are made with InGaAIN Vertical Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.



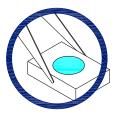
Package Dimensions

SPEC NO: DSAH9588 APPROVED: WYNEC REV NO: V.2 CHECKED: Allen Liu DATE: JAN/14/2008 DRAWN: R.Chen PAGE: 1 OF 6 ERP: 1201003020

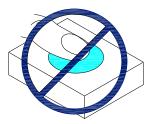
Handling Precautions

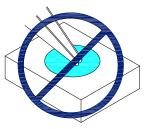
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

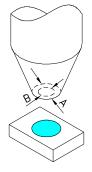




3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratch the silicone lens or damage the internal circuitry.



- 4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



Selection Guide lv (mcd) [2] @ 150mA Φv (mlm) [2] Viewing @ 150mA Angle [1] Dice Part No. Lens Type Min. Тур. Min. Тур. 2 0 1/2 AA3529ZG24ZS GREEN (InGaAIN) WATER CLEAR 6700 7500 18000 21000 120 °

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

2. Luminous Intensity / Luminous Flux: +/-15%.

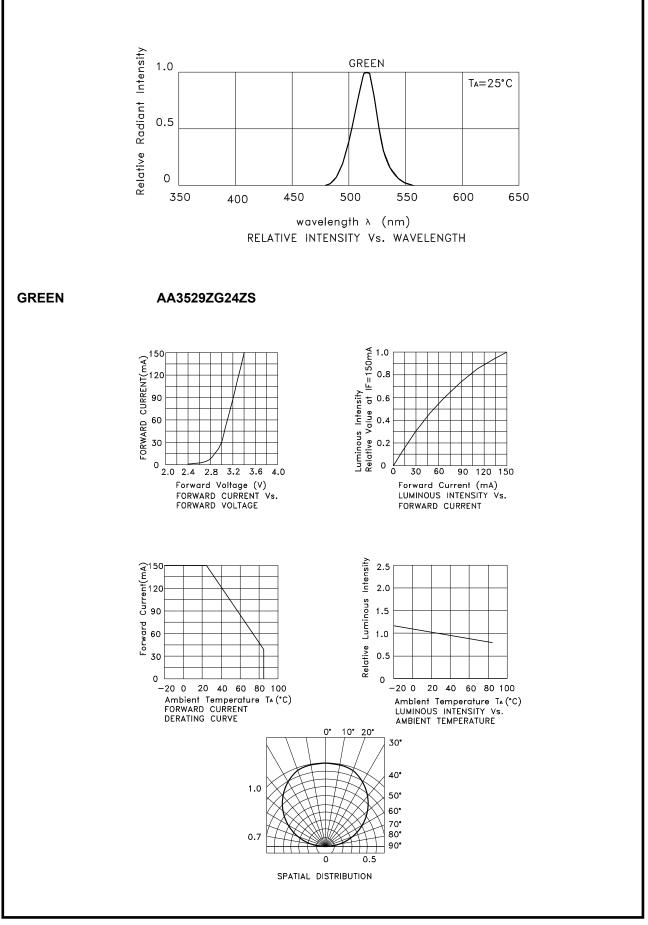
Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λ peak	Peak Wavelength	Green	515		nm	IF=150mA
λ D [1]	Dominant Wavelength	Green	525		nm	IF=150mA
Δλ 1/2	Spectral Line Half-width	Green	30		nm	IF=150mA
С	Capacitance	Green	45		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Green	3.4	3.8	V	IF=150mA

Notes: 1. Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

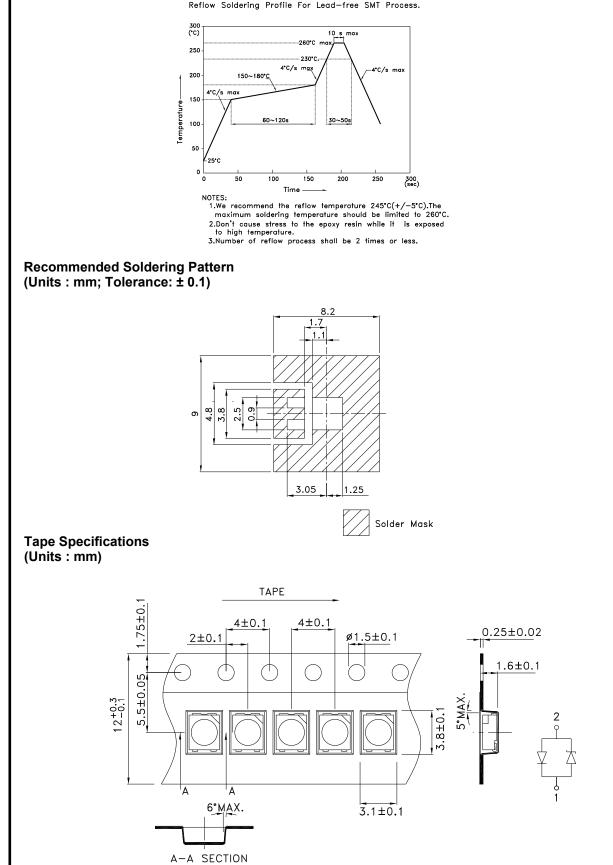
Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units
Power dissipation	570	mW
DC Forward Current	150	mA
Thermal Resistance	170	°C/W
Operating/Storage Temperature	-40°C To +85°C	



AA3529ZG24ZS

Reflow Soldering Profile For Lead-free SMT Process.



REV NO: V.2 **CHECKED: Allen Liu** DATE: JAN/14/2008 **DRAWN: R.Chen**

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